

# FMP05N60E

FUJI POWER MOSFET

## Super FAP-E<sup>3</sup> series

## N-CHANNEL SILICON POWER MOSFET

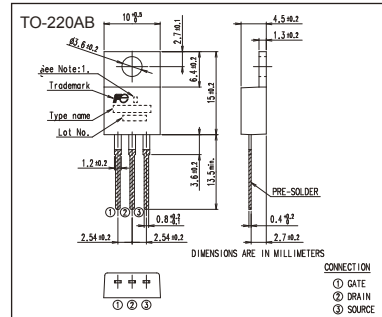
### Features

- Maintains both low power loss and low noise
- Lower R<sub>DS(on)</sub> characteristic
- More controllable switching dv/dt by gate resistance
- Smaller V<sub>GS</sub> ringing waveform during switching
- Narrow band of the gate threshold voltage (3.0±0.5V)
- High avalanche durability

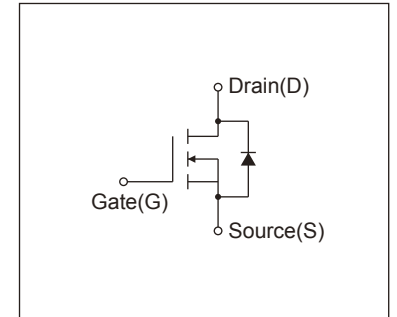
### Applications

- Switching regulators
- UPS (Uninterruptible Power Supply)
- DC-DC converters

### Outline Drawings [mm]



### Equivalent circuit schematic



### Maximum Ratings and Characteristics

#### Absolute Maximum Ratings at T<sub>c</sub>=25°C (unless otherwise specified)

Description	Symbol	Characteristics	Unit	Remarks
Drain-Source Voltage	V <sub>DS</sub>	600	V	
	V <sub>DSX</sub>	600	V	V <sub>GS</sub> = -30V
Continuous Drain Current	I <sub>D</sub>	±5.5	A	
Pulsed Drain Current	I <sub>DP</sub>	±22	A	
Gate-Source Voltage	V <sub>GS</sub>	±30	V	
Repetitive and Non-Repetitive Maximum Avalanche Current	I <sub>AR</sub>	5.5	A	Note*1
Non-Repetitive Maximum Avalanche Energy	E <sub>AS</sub>	262	mJ	Note*2
Repetitive Maximum Avalanche Energy	E <sub>AR</sub>	9.0	mJ	Note*3
Peak Diode Recovery dv/dt	dv/dt	4.2	kV/μs	Note*4
Peak Diode Recovery -di/dt	-di/dt	100	A/μs	Note*5
Maximum Power Dissipation	P <sub>D</sub>	2.02	W	T <sub>a</sub> =25°C
		90		T <sub>c</sub> =25°C
Operating and Storage Temperature range	T <sub>ch</sub>	150	°C	
	T <sub>stg</sub>	-55 to + 150	°C	

#### Electrical Characteristics at T<sub>c</sub>=25°C (unless otherwise specified)

Description	Symbol	Conditions	min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	600	-	-	V
Gate Threshold Voltage	V <sub>GS</sub> (th)	I <sub>D</sub> =250μA, V <sub>DS</sub> =V <sub>GS</sub>	2.5	3.0	3.5	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =600V, V <sub>GS</sub> =0V	-	-	25	μA
		V <sub>DS</sub> =480V, V <sub>GS</sub> =0V	-	-	250	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	-	10	100	nA
Drain-Source On-State Resistance	R <sub>DS</sub> (on)	I <sub>D</sub> =2.8A, V <sub>GS</sub> =10V	-	1.11	1.30	Ω
Forward Transconductance	g <sub>fs</sub>	I <sub>D</sub> =2.8A, V <sub>DS</sub> =25V	3	6	-	S
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V	-	1020	1530	pF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> =0V	-	95	143	
Reverse Transfer Capacitance	C <sub>rss</sub>	f=1MHz	-	7	10.5	
Turn-On Time	td(on)	V <sub>cc</sub> =300V	-	11	16.5	ns
	tr	V <sub>GS</sub> =10V	-	8.5	13	
Turn-Off Time	td(off)	I <sub>D</sub> =2.8A	-	80	120	
	tf	R <sub>G</sub> =24Ω	-	17	25.5	
Total Gate Charge	Q <sub>G</sub>	V <sub>cc</sub> =300V	-	33	50	nC
Gate-Source Charge	Q <sub>GS</sub>	I <sub>D</sub> =5.5A	-	8.5	13	
Gate-Drain Charge	Q <sub>GD</sub>	V <sub>GS</sub> =10V	-	9.5	14.5	
Avalanche Capability	I <sub>AV</sub>	L=6.35mH, T <sub>ch</sub> =25°C	5.5	-	-	A
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =5.5A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C	-	0.86	1.30	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =5.5A, V <sub>GS</sub> =0V	-	0.4	-	μs
Reverse Recovery Charge	Q <sub>rr</sub>	-di/dt=100A/μs, T <sub>ch</sub> =25°C	-	3.0	-	μC

#### Thermal Characteristics

Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	R <sub>th</sub> (ch-c)	Channel to Case			1.390	°C/W
	R <sub>th</sub> (ch-a)	Channel to Ambient			62.0	°C/W

Note \*1 : T<sub>ch</sub>≤150°C

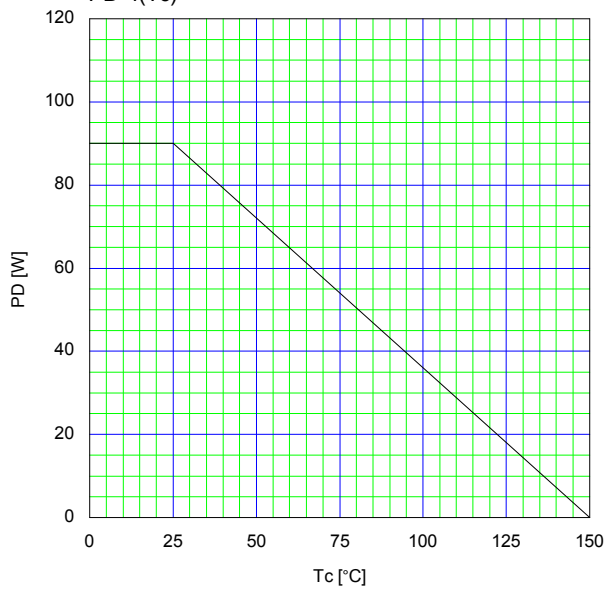
Note \*2 : Stating T<sub>ch</sub>=25°C, I<sub>AS</sub>=2.2A, L=99.2mH, V<sub>cc</sub>=60V, R<sub>G</sub>=50Ω  
E<sub>AS</sub> limited by maximum channel temperature and avalanche current.  
See to 'Avalanche Energy' graph.

Note \*3 : Repetitive rating : Pulse width limited by maximum channel temperature.  
See to the 'Transient Thermal Impedance' graph.

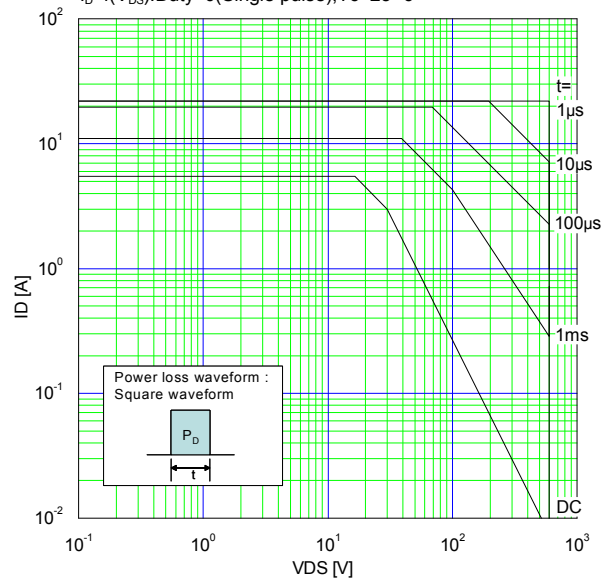
Note \*4 : I<sub>F</sub>≤I<sub>D</sub>, -di/dt=100A/μs, V<sub>cc</sub>≤BV<sub>DSS</sub>, T<sub>ch</sub>≤150°C.

Note \*5 : I<sub>F</sub>≤I<sub>D</sub>, dv/dt=4.2kV/μs, V<sub>cc</sub>≤BV<sub>DSS</sub>, T<sub>ch</sub>≤150°C.

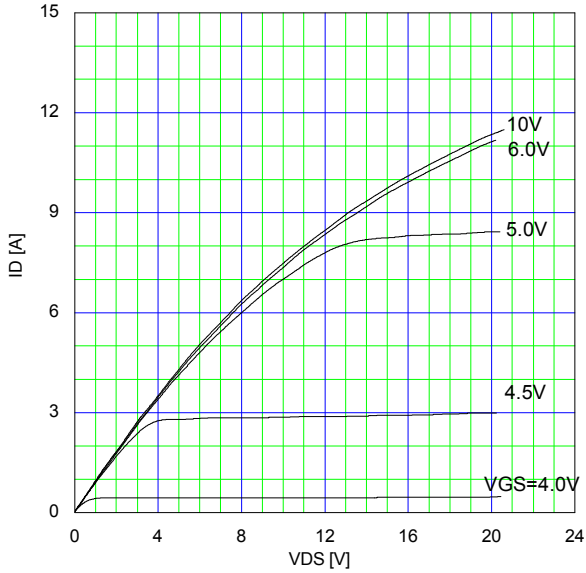
Allowable Power Dissipation  
 $PD=f(T_c)$



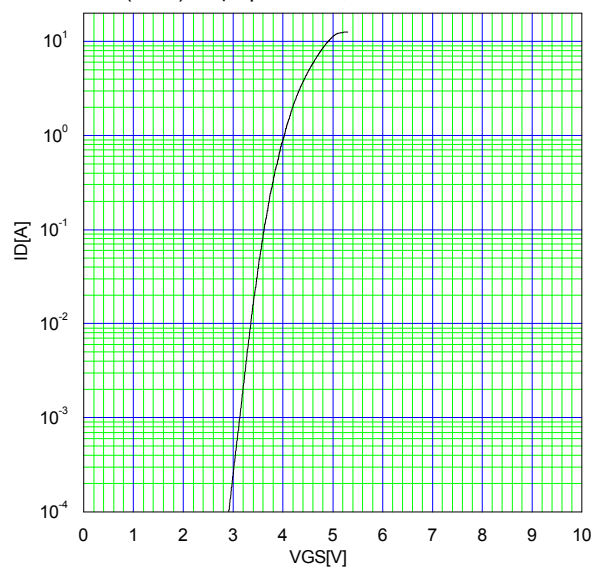
Safe Operating Area  
 $I_D=f(V_{DS}):Duty=0(\text{Single pulse}),T_c=25\text{ }^\circ\text{C}$



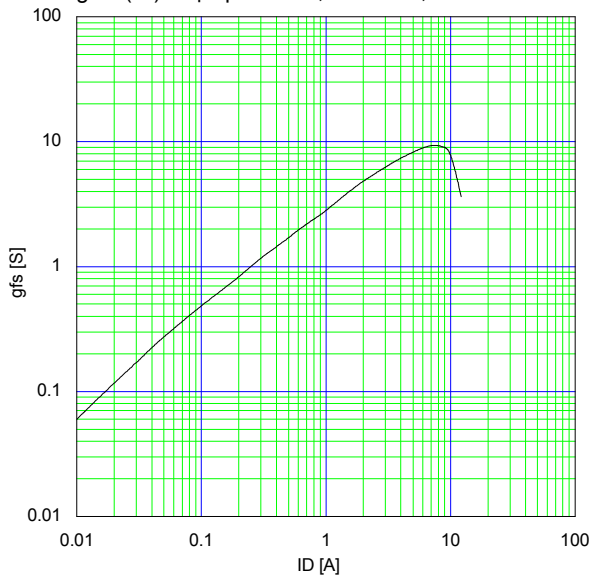
Typical Output Characteristics  
 $I_D=f(V_{DS}):80\text{ }\mu\text{s pulse test},T_{ch}=25\text{ }^\circ\text{C}$



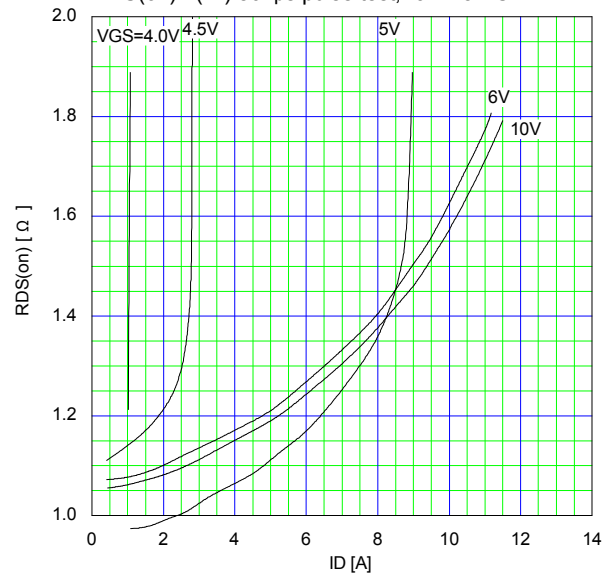
Typical Transfer Characteristic  
 $I_D=f(V_{GS}):80\text{ }\mu\text{s pulse test},V_{DS}=25\text{V},T_{ch}=25\text{ }^\circ\text{C}$



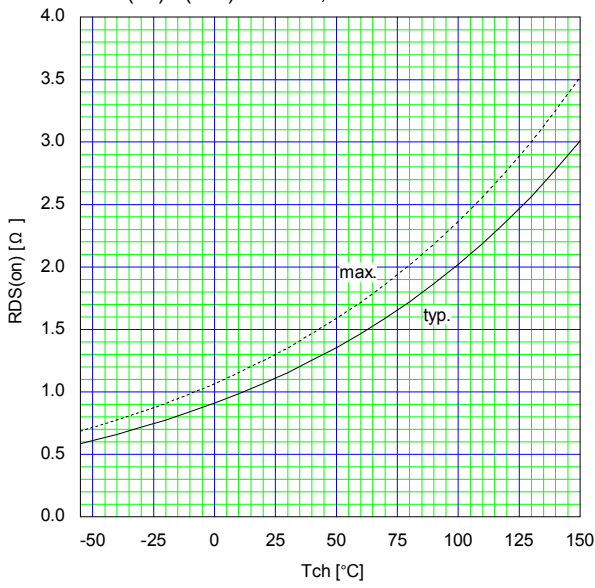
Typical Transconductance  
 $g_{fs}=f(I_D):80\text{ }\mu\text{s pulse test},V_{DS}=25\text{V},T_{ch}=25\text{ }^\circ\text{C}$



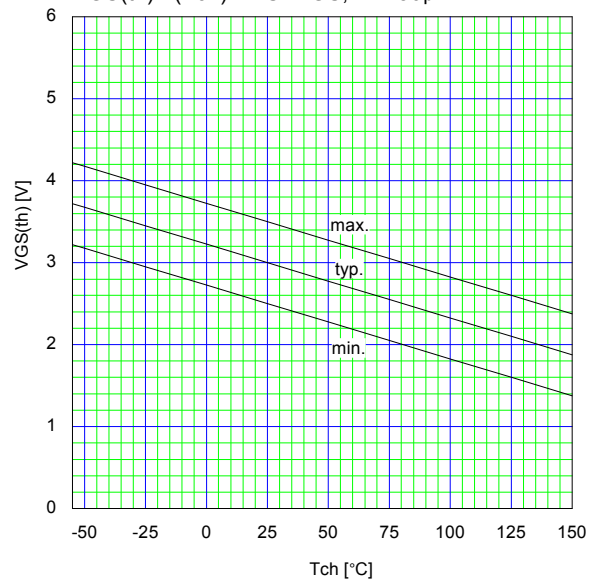
Typical Drain-Source on-state Resistance  
 $R_{DS(on)}=f(I_D):80\text{ }\mu\text{s pulse test},T_{ch}=25\text{ }^\circ\text{C}$



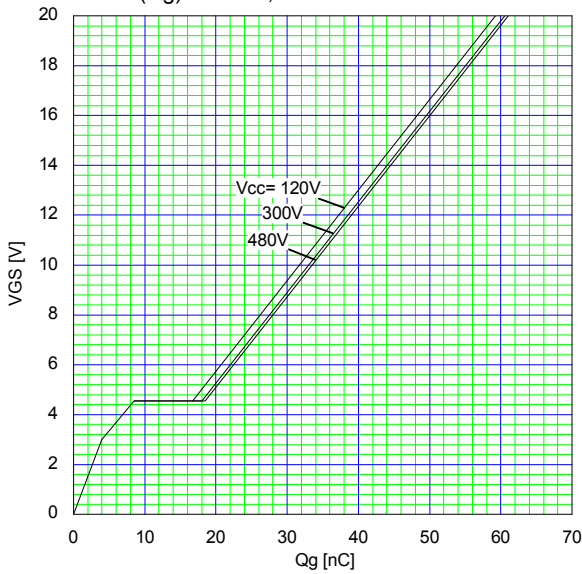
Drain-Source On-state Resistance  
 $R_{DS(on)} = f(T_{ch}) : I_D = 2.8A, V_{GS} = 10V$



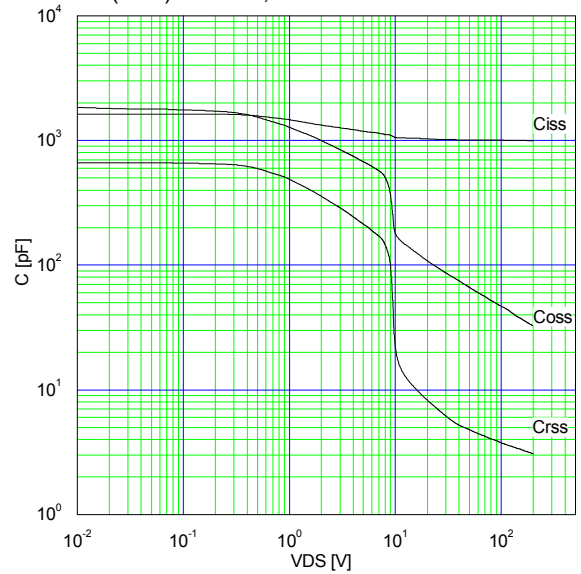
Gate Threshold Voltage vs. T<sub>ch</sub>  
 $V_{GS(th)} = f(T_{ch}) : V_{DS} = V_{GS}, I_D = 250\mu A$



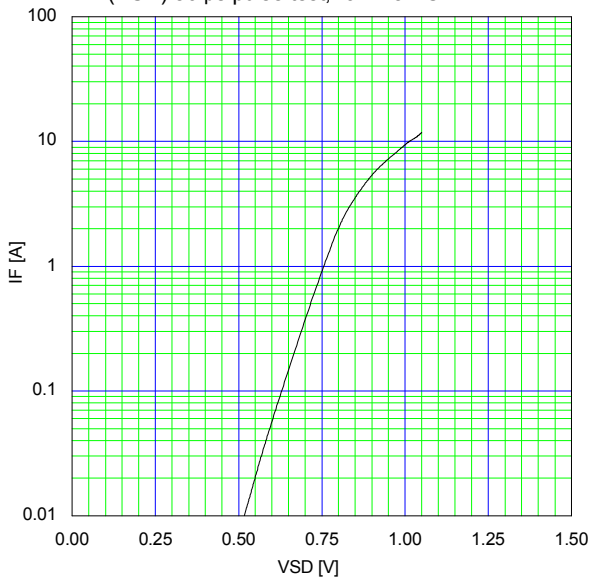
Typical Gate Charge Characteristics  
 $V_{GS} = f(Q_g) : I_D = 5.5A, T_{ch} = 25\text{ °C}$



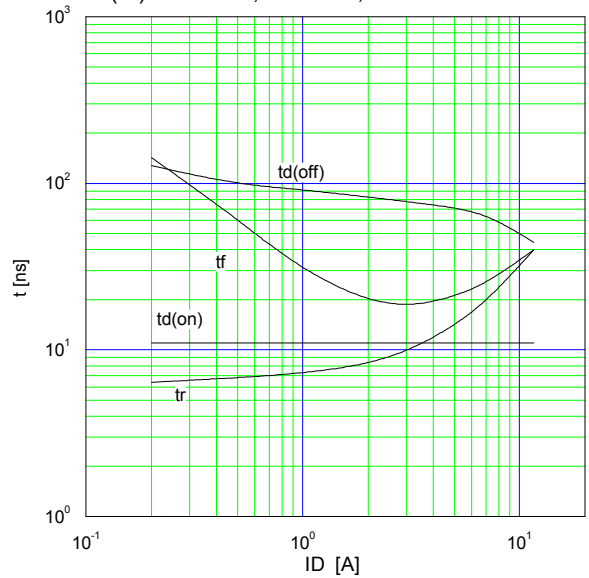
Typical Capacitance  
 $C = f(V_{DS}) : V_{GS} = 0V, f = 1MHz$



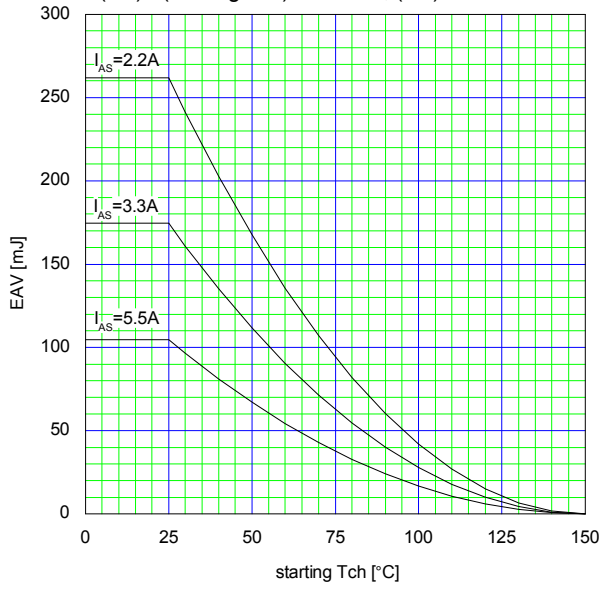
Typical Forward Characteristics of Reverse Diode  
 $I_F = f(V_{SD}) : 80\text{ }\mu s\text{ pulse test}, T_{ch} = 25\text{ °C}$



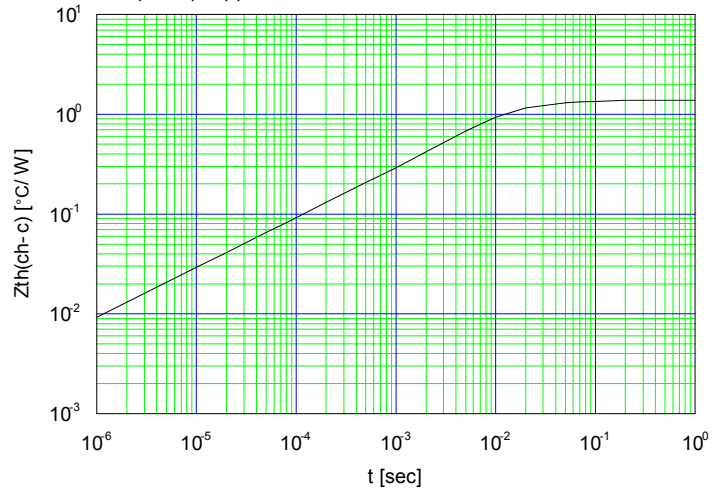
Typical Switching Characteristics vs. I<sub>D</sub>  
 $t = f(I_D) : V_{cc} = 300V, V_{GS} = 10V, R_G = 24\text{ }\Omega$



Maximum Avalanche Energy vs. starting Tch  
 $E(AV)=f(\text{starting Tch}): V_{cc}=60V, I(AV) \leq 5.5A$



Transient Thermal Impedance  
 $Z_{th}(ch-c)=f(t): D=0$



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